



## P-Channel 12 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)Max.$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
	0.640 at V <sub>GS</sub> = - 4.5 V	- 0.48				
- 12	0.880 at V <sub>GS</sub> = - 2.5 V	- 0.41				
	1.200 at V <sub>GS</sub> = - 1.8 V	- 0.35	1.15 nC			
	1.443 at V <sub>GS</sub> = - 1.5 V	- 0.10				
	2.475 at V <sub>GS</sub> = - 1.2 V	- 0.05				

#### **FEATURES**

- TrenchFET® Power MOSFET
- Typical ESD protection: 700 V (HBM)
- Fast Switching Speed
- Material categorization:

For definitions of compliance please see www.vishay.com/doc?99912

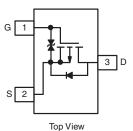


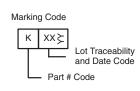


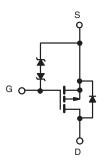
#### **APPLICATIONS**

- Portable Devices such as Smart Phones, Tablet PCs and Mobile Computing
  - Load Switch for Low Voltage Gate Drive
  - Load Switch for 1.2 V Power Line

## SC-89 (3-LEADS)







Ordering Information: Si1011X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 12	V			
Gate-Source Voltage		V <sub>GS</sub>	± 5	v		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	1-	- 0.48 <sup>b, c</sup>			
Continuous Drain Current (1) = 130 °C)	T <sub>A</sub> = 70 °C	l <sub>D</sub>	- 0.38 <sup>b, c</sup>			
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	- 1.5	A .		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub> - 0.16 <sup>b, c</sup>				
Maximum Dayyar Dissination	T <sub>A</sub> = 25 °C	В	0.19 <sup>b, c</sup>	w		
Maximum Power Dissipation	T <sub>A</sub> = 70 °C	P <sub>D</sub>	0.12 <sup>b, c</sup>	VV		
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C			

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Manifestor Longition to Aughtenia h	t ≤ 5 s	B	440	530	°C/W	
Maximum Junction-to-Ambient <sup>a, b</sup>	Steady State	$R_{thJA}$	540	650	] 5/44	

- a. Maximum under steady state conditions is 650 °C/W.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			•				
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0$ , $I_D = -250 \mu A$	- 12			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA		- 7		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 <sub>D</sub> = - 250 μΑ		1.7			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.35		- 0.8	V	
Cata Source Leakage	1	$V_{DS} = 0 V, V_{GS} = \pm 5 V$		± 10			
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 4.5 V$			± 1		
Zava Cata Valtaga Dirain Current	1	V <sub>DS</sub> = - 12 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = - 12 V, $V_{GS}$ = 0 V, $T_{J}$ = 85 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le$ - 5 V, $V_{GS} =$ - 4.5 V	- 1.5			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 0.4 A		0.530	0.640		
		V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 0.2 A		0.730	0.880	=	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.1 A		0.920	1.200	Ω	
		V <sub>GS</sub> = - 1.5 V, I <sub>D</sub> = - 0.05 A		1.100	1.443		
		V <sub>GS</sub> = - 1.2 V, I <sub>D</sub> = - 0.05 A		1.650	2.475	1	
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = - 6 V, I <sub>D</sub> = - 0.4 A		1		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			62		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		26			
Reverse Transfer Capacitance	C <sub>rss</sub>			20			
Total Cata Channa		$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.4 \text{ A}$		2	4		
Total Gate Charge	$Q_{g}$			1.15	2	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -6 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -0.4 \text{ A}$		0.37			
Gate-Drain Charge	$Q_{gd}$			0.43			
Gate Resistance	$R_g$	f = 1 MHz		12		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			4	8		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 6 V, $R_L$ = 20 $\Omega$		11	20	ns	
Turn-Off DelayTime	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong\text{-}\ \text{0.3 A, V}_\text{GEN}=\text{-}\ \text{5 V, R}_g=\text{1}\ \Omega$		9	18		
Fall Time	t <sub>f</sub>			9	18		
<b>Drain-Source Body Diode Characteris</b>	tics						
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 1.5	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 0.3 A		- 0.8	- 1.2	٧	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			12	20	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 - 0.3 A dl/dt 100 A/vs		5	10	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -0.3 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		7			
Reverse Recovery Rise Time	t <sub>b</sub>	7		5		ns	

### Notes:

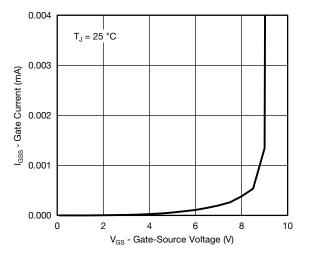
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

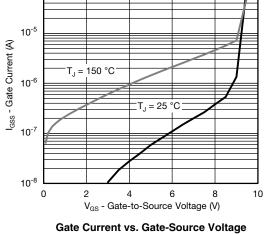
b. Guaranteed by design, not subject to production testing.



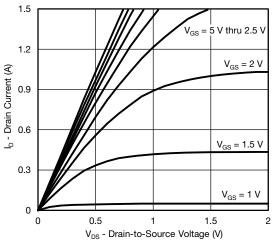
## P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



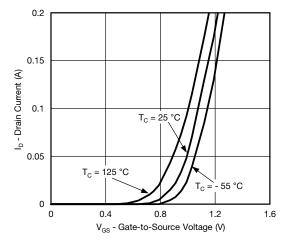
### Gate Current vs. Gate-Source Voltage



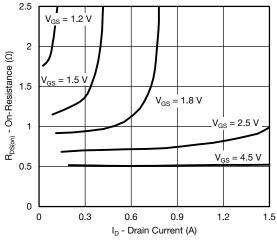
10<sup>-4</sup>



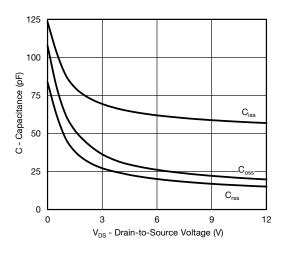
**Output Characteristics** 



**Transfer Characteristics** 



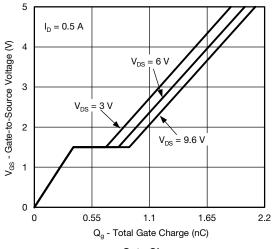
On-Resistance vs. Drain Current



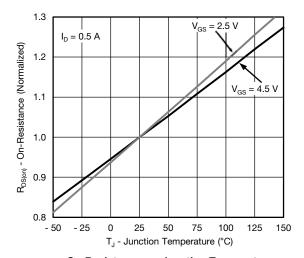
Capacitance

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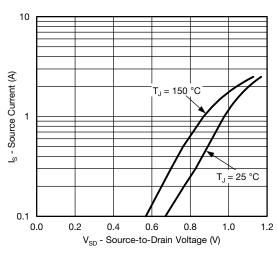
## P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



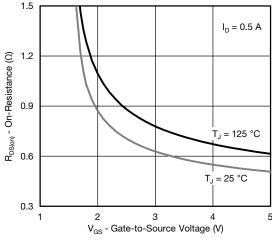




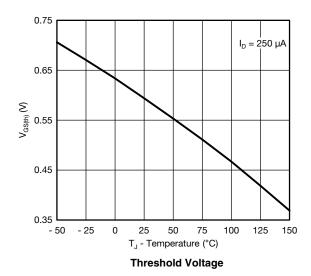
On-Resistance vs. Junction Temperature

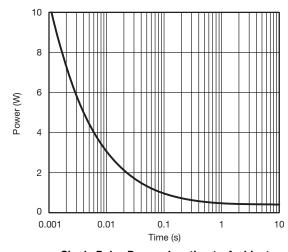


Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

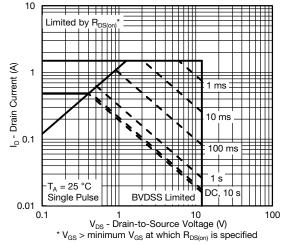


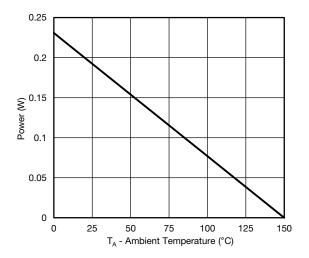


Single Pulse Power, Junction-to-Ambient



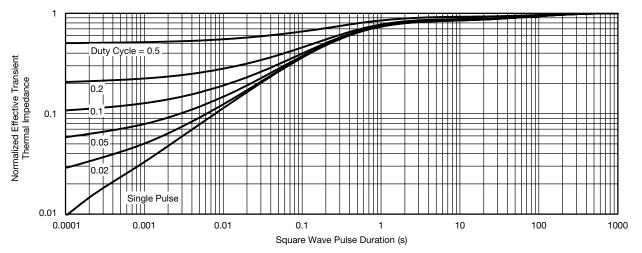
## P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

Power Derating, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

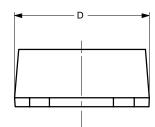
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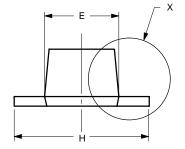


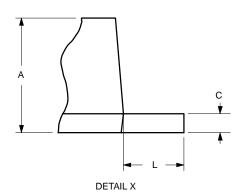


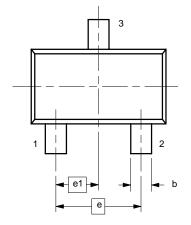
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## SC89-3





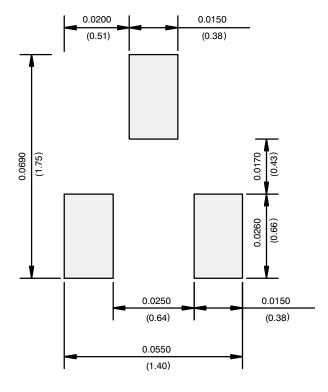




	MILLIM	IETERS	INC	CHES	
Dim	Min	Max	Min	Max	
Α	0.60	0.80	0.024	0.031	
b	0.23	0.33	0.009	0.013	
С	0.10	0.20	0.004	0.008	
D	1.50	1.70	0.059	0.067	
Е	0.75	0.95	0.030	0.037	
е	1.00 BSC		0.040 BSC		
e <sub>1</sub>	0.50 BSC		0.020	BSC	
Н	1.50	1.70	0.059	0.067	
L	0.30	0.50	0.012	0.020	
ECN: S-03946—Rev. B, 09-Jul-01 DWG: 5869					



## **RECOMMENDED MINIMUM PADS FOR SC-89: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

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